



ALPHA & OMEGA
SEMICONDUCTOR

Alpha & Omega Semiconductor Product Reliability Report

5.0SMDJ12A, rev A

Plastic Encapsulated Device

ALPHA & OMEGA Semiconductor, Inc

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This AOS product reliability report summarizes the qualification result for 5.0SMDJ12A. Accelerated environmental tests are performed on a specific sample size, and then followed by electrical test at end point. Review of final electrical test result confirms that 5.0SMDJ12A passes AOS quality and reliability requirements. The released product will be categorized by the process family and be routine monitored for continuously improving the product quality.

I. Reliability Stress Test Summary and Results

Test Item	Test Condition	Time Point	Total Sample Size	Number of Failures	Reference Standard
HTRB	Temp = 150°C , VR=11.20V	1000 hours	22 pcs	0	JESD22-A108
Autoclave	121°C , 29.7psia, RH=100%	48 hours	22 pcs	0	JESD22-A102
Temperature Cycle	-55°C to 150°C , air to air,	500 cycles	22 pcs	0	JESD22-A104
HTSL	Temp = 175°C	1000 hours	22 pcs	0	JESD22-A103
Solderability Test	Temp = 245°C	5 seconds	5 pcs	0	JESD22-B102
RSH	Temp = 260°C	10 seconds	5 pcs	0	JESD22-B106

Note: The reliability data presents total of available generic data up to the published date.

II. Reliability Evaluation

FIT rate (per billion): 160.25

MTTF = 712 years

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size. Failure Rate Determination is based on JEDEC Standard JESD 85. FIT means one failure per billion hours.

Failure Rate = $\text{Chi}^2 \times 10^9 / [2 (N) (H) (Af)] = 160.25$

MTTF = $10^9 / \text{FIT} = 712$ years

Chi² = Chi Squared Distribution, determined by the number of failures and confidence interval

N = Total Number of units from burn-in tests

H = Duration of burn-in testing

Af = Acceleration Factor from Test to Use Conditions (Ea = 0.7eV and Tuse = 55°C)

Acceleration Factor [**Af**] = $\text{Exp} [Ea / k (1/Tj u - 1/Tj s)]$

Acceleration Factor ratio list:

	55 deg C	70 deg C	85 deg C	100 deg C	115 deg C	130 deg C	150 deg C
Af	259	87	32	13	5.64	2.59	1

Tj s = Stressed junction temperature in degree (Kelvin), K = C+273.16

Tj u = The use junction temperature in degree (Kelvin), K = C+273.16

k = Boltzmann's constant, 8.617164 X 10⁻⁵eV / K